

Title (en)

MICROPROTRUSION ARRAY AND METHODS OF MAKING A MICROPROTRUSION

Title (de)

MIKROVORSPRUNGSARRAY UND VERFAHREN ZUR HERSTELLUNG EINES MIKROVORSPRUNGS

Title (fr)

RESEAU DE MICROPROTUBERANCES ET PROCEDES DE FORMATION D'UNE MICROPROTUBERANCE

Publication

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Application

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Abstract (en)

[origin: WO02062202A2] A microprotrusion array is formed from a silicon wafer by a plurality of sequential plasma and wet isotropic and anisotropic etching steps. The resulting microprotrusions have sharpened tips or cutting edges formed by a wet isotropic etch.

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